

# BOUT COMPANY

ROOTS Materials was established by experienced and passionate engineers to serve as a foundation for our customers' success in the LED and semiconductor manufacturing industries



### Vision

| To be the global leader in innovative phosphor technologies, revolutionizing the LED industry with the highest quality PiG solutions

| To illuminate the world with cutting-edge phosphor in glass technology, setting new standards for excellence in the global market

| To drive the future of lighting technology by pioneering the most advanced and sustainable PiG solutions worldwide.

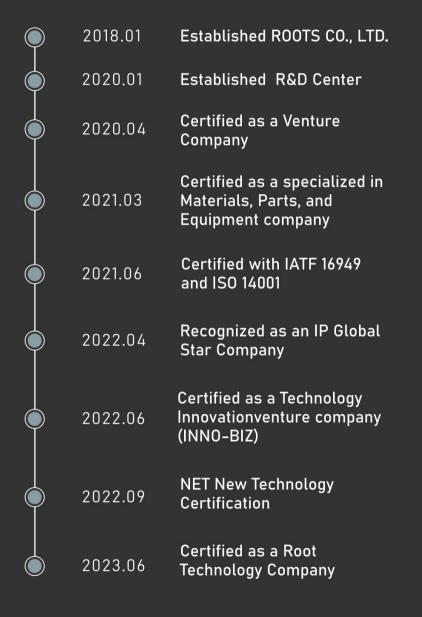
### **Mission**

To deliver unparalleled PiG products through our unique manufacturing process, ensuring superior performance and customer satisfaction across the globe

To innovate relentlessly, offering the best phosphor in glass solutions that meet the evolving needs of our global customers

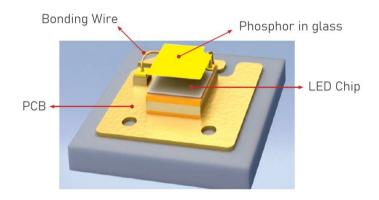
To provide high-quality, reliable, and efficient PiG solutions that empower our clients to excel in the competitive LED industry.

### History



### PIG PHOSPHOR IN GLASS

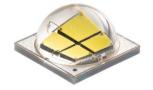
Our PiG (Phosphor in Glass) products, which we develop and manufacture, are designed for high-power, high-reliability lighting applications such as automotive headlights, medical lights, projectors, etc.. Unlike liquid silicone-based phosphors like PiS (Phosphor in Silicone), which are used in medium and low-power applications such as general lighting, our PiG technology is optimized for these more demanding environments.

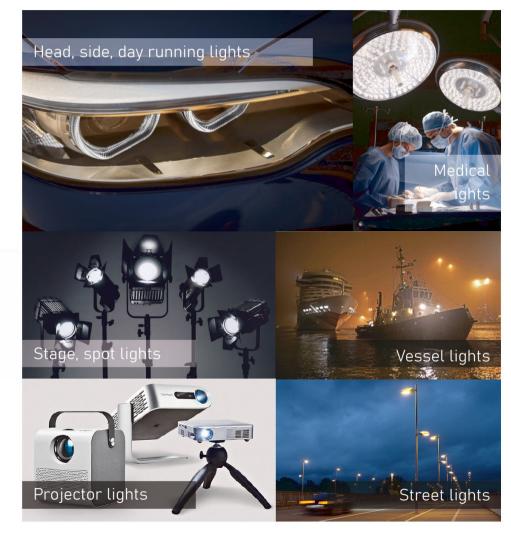


# Suitable Applications Automobile Exterior High reliability products VOCs free products









PRECISE DIMENSION CONTROL 100% CHIP QUALITY INSEPCTION 100% COLOR INSPECTION NO CHIPPING ON SURFACE EDGE

Supporting white, amber color Supporting both vertical and flip chip type
Offering size, thickness customization service R&D development support for new product

### **ALL IN-HOUSE PROCESS**

### WAFER FABRICATION GLASS, PHOSPHOR MIXING 1st/2nd SINTERING

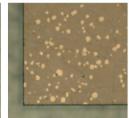
## CHIP FABRICATION WAFER GRIDNING WAFER POLISHING DICING SORTING (BINNING)

### **QUALITY INSPECTION**

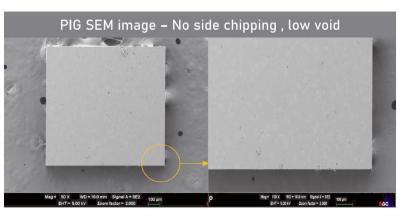
AUTOMATED VISUAL INSPECTION TARGET COLOR INSPECTION 100% CHIP INSPECTION



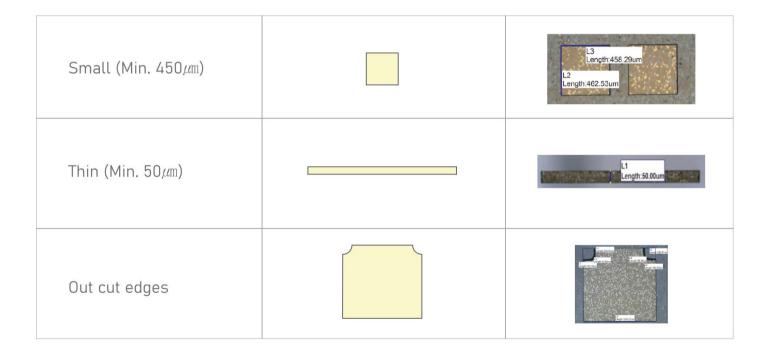








We possess proprietary technology for the production of PiG (Phosphor in Glass). Based on this, we are capable of developing and manufacturing ultra-small and ultra-thin PiG. Additionally, we can produce PiG in various forms. We are open to collaborating with customers on new development projects that lead the market



ROOTS proprietary PiG processing technology offers a variety of structures suitable for enhancing optical properties.

Reflection edge	
Angle-cut	
Various shapes	

# CHEMICAL SOLUTIONS

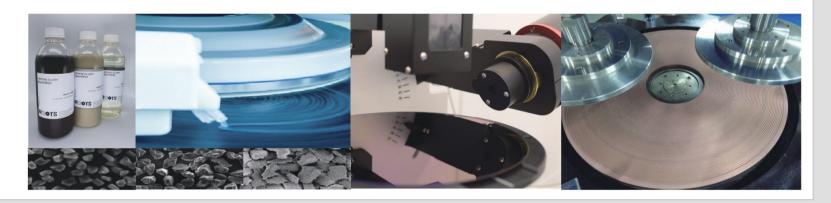
We develop and provide the most efficiently customized oil and water base diamond slurries

### **OIL/WATER BASE DIAMOND SLURRIES**

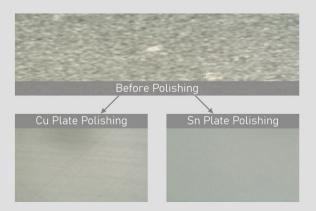
DIAMOND TYPE: MONO, POLY, BLAST

POSSBILE SIZE : 1.0 - 20µm

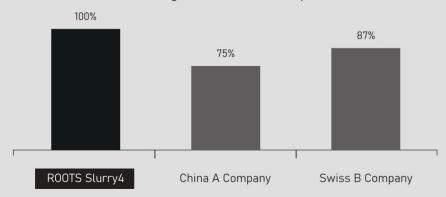
POLISHING FOR SAPPHIRE WAFER AND CERAMIC BASE PARTS VISCOSTY, DIAMOND DISTRIBUTION RATE CONTROL OFFERING ANY CUMSTOMIZED PRODUCTS



### Wafwe Backside Condition Before/After Polishing



### Diamond Slurry Polishing Removal Rate Comparison



### Flux Cleaning Solution

pH Neutral cleaner based on Water soluble

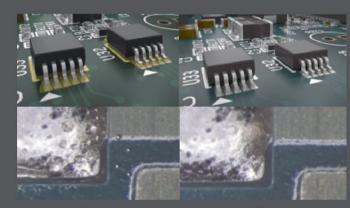
Application for all kinds of cleaning methods (Inline & Batch Type, Spray)
Perfect cleaning for flux residue

Anti Corrosion & High compatibility for sensitive Metals

- Aluminum, Copper, Nikel, Plastic & Inks

Application & Merit

- LED Module, Power Module, Flip Chip & PKG
- Improve wire bondability and Soldering quality
- Improve encapsulation quality of Power components and soldering



Before	After

Specific Gravity	(g/ccm) at 20°C/68°F	0.96
Surface tension	(mN/m) at 25°C/77°F	29.1
Boiling point	°C/°F	98 - 229°C /208 - 444°F
Flash point	°C/°F	None until boiling
рН	10g/l H20	7.02
Vapor pressure	(mbar) at 20°C/68°F	약 20
Cleaning Temp.	°C/°F	40 - 70°C / 104 - 158°F
Solubility	-	Yes
Concentration for inline spray	Concentration	7.5 – 20 %
Concentration for Batch	Concentration	10 – 25 %
HMIS Grade	Health risk – Flammability – Reactivity	0 - 0 - 0

### Solder Mask Cleaner

Eco-Friendly Cleaner

- Heavy metal / Halogen (Cl, F, Br .. ) / VOC regulated substances "Free "
- No Rohs / Environmental issues due to environmentally friendly materials
- Low evaporation rate

Solvent	Evaporation Rate
DI water	0.36
RMC-001	0.65
IPA	2.5

### **Material Property**

Solvent	Evaporation Rate	
Appearance	0.36	
Density	0.45	
рН	0.65	
Flash point	None	
Oduor	Mild ether like	
Storage condition	Room Temp (5~30°C)	
Guarantee	1year with closed containers	





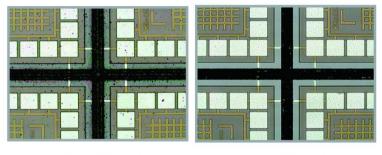
### LASER DICING COATING SOLUTION

Part Number: RLC-B01, RLC-B02

Coating solution for protecting wafer from

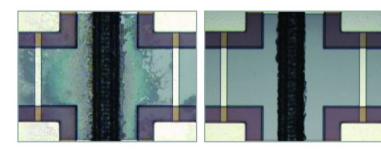
particles & thermal damage during laser dicing process

- Water soluble material
- Spin coating before laser process
- Cleaning with D.I water
- Stable coating layer
- No Debris , HAZ after laser process



Before Cleaning

After Cleaning



Without Coating

With Coating

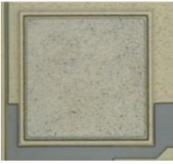
ITEM	Specification		Remarks
TIEM	RLC-801	RLC-802	Remarks
Main component	Polyvinyl pyrrolidone (PVP)	Polyvinyl pyrrolidone (PVP)	
Appearance	Clear or Slightly yellowish	Clear or Slightly yellowish	Visual test
pH(at 20°C)	3.0~5.0	3.0~5.0	pH meter (Orion Star A211)
Specific Gravity (at 20℃)	1.01~1.03	1.01~1.03	Hydrometer Fisher Scientific
Viscosity (cps at 25℃)	220~260	260~300	Remark)¹

■ Remark)¹ Brookfiled Viscometer (DV-II+Pro, Spindle No.62, 120rpm)

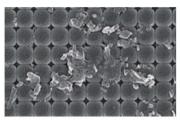
### **SURFACTANT**

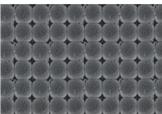
Protect wafer from corrosion and particle contamination Reducing chipping and crack, improving blade life time Low consumption by dilution











D I Water + Surfactant

Without Surfactant

With Surfactant

Without Surfactant

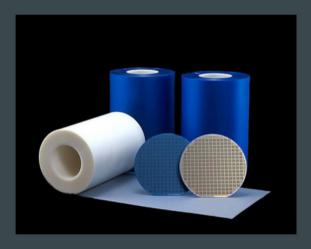
With Surfactant

- Protect wafer from corrosion and particle contaminations by coating wafer surface
- Provide low frictional force by high lubrication property:
   Reduced chipping & crack / Improved blade life-time
- Prevent static charge by controlling D-I water resistance
- · Reduce pad corrosion and galvanic cell
- Comparatively low consumption by dilution

ltem	Description
Main Ingredient	Nonionic Surfactant
pH (at 20 °C)	5~6
Specific Gravity (at 20℃)	1.02~1.03

### Tapes

### **Distribution**



### UV Tape (H-Series)

- -Easy detachment after UV radiation
- -Tape Material: PO, PET (Thickness and adhesion can be customized)

### Non-UV Tape (L-Series)

-High expansion and low adhesion / Suitable for chip temporary fix

### Thermal Release Tape (K-Series / Denka Counter Parts)

- -Extremely thin grinding capability.
- -Eliminates warping and sagging by firmly supporting the wafer.
- -Easily releases at any time with heat treatment

# Wheels Distribution



### Silicone grinding wheel

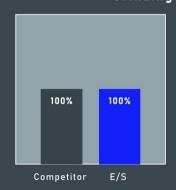
- -Wafer surface roughness and die strength can be improved
- -Grinding stress and wafer edge chipping can be reduced
- -Diamond at the tip can be distributed consistently
- -Possible to grind Si wafer up to 17um (Ultra thin wafer)

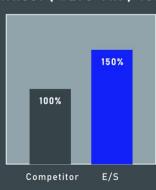


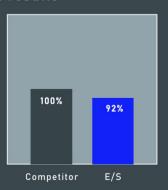
Ceramic and Glass grinding wheel

- -Leading technology in various types of machines and applications
- -Rough wheel (Metal bond): Long life time and excellent bulk removal rate
- -Fine wheel (Vitrified bond): Superior grinding ability and roughness
- -Providing proper wheel designs for various grinding methods and proper recipes

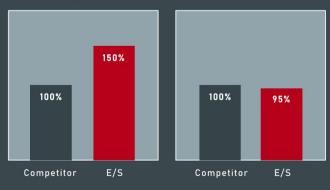
### Grinding wheel (#270-MX) Test results







### Grinding wheel (#400-MX) Test results



### CONTACT

### Location

92 Euncheong-ro, Namdong-gu, Incheon City 21644 Korea Tel. 82-32-225-0671 / 82-10-6602-6980

Email : chase@rootsmaterials.com www.rootsmaterials.com

# ROOTS